

SEMITRANS[®] 2

IGBT Modules

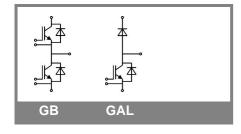
SKM 145GB123D SKM 145GAL123D

Features

- MOS input (voltage controlled)
- N channel, Homogeneous Si
- · Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (10 mm) and creepage distances (20 mm)

Typical Applications*

- Switching (not for linear use)
- AC inverter drives



| Absolute | Maximum Ratings | T _c = | 25 °C, unless otherwise | specified |
|-------------------|---|---------------------------|-------------------------|-----------|
| Symbol | Conditions | | Values | Units |
| IGBT | | | | |
| V_{CES} | T _j = 25 °C T _i = 150 °C | | 1200 | V |
| I _C | T _j = 150 °C | T _{case} = 25 °C | 145 | Α |
| | | T _{case} = 80 °C | 110 | Α |
| I _{CRM} | I _{CRM} =2xI _{Cnom} | | 200 | Α |
| V _{GES} | | | ± 20 | V |
| t _{psc} | V_{CC} = 600 V; $V_{GE} \le 20$ V; $V_{CES} < 1200$ V | T _j = 125 °C | 10 | μs |
| Inverse [| Diode | | | |
| I_{F} | T _j = 150 °C | T_{case} = 25 °C | 130 | Α |
| | | T _{case} = 80 °C | 90 | Α |
| I_{FRM} | I _{FRM} =2xI _{Fnom} | | 200 | Α |
| I _{FSM} | $t_p = 10 \text{ ms}; \sin.$ | T _j = 150 °C | 900 | Α |
| Freewhe | eling Diode | | | • |
| I_{F} | T _j = 150 °C | T_{case} = 25 °C | 170 | Α |
| | | T_{case} = 80 °C | 115 | Α |
| I _{FRM} | I _{FRM} =2xI _{Fnom} | | 300 | Α |
| I _{FSM} | $t_p = 10 \text{ ms; sin.}$ | T _j = 150 °C | 1440 | А |
| Module | | | • | |
| $I_{t(RMS)}$ | | | 200 | Α |
| T _{vj} | | | - 40+ 150 | °C |
| T _{stg} | | | - 40+ 125 | °C |
| V _{isol} | AC, 1 min. | | 2500 | V |

| Characteristics T _c = | | 25 °C, unless otherwise specified | | | | |
|----------------------------------|---|--|------|------|------|-------|
| Symbol | Conditions | | min. | typ. | max. | Units |
| IGBT | | | | | | |
| $V_{GE(th)}$ | $V_{GE} = V_{CE}$, $I_C = 4 \text{ mA}$ | | 4,5 | 5,5 | 6,5 | V |
| I _{CES} | $V_{GE} = 0 V, V_{CE} = V_{CES}$ | T _j = 25 °C T _j = 25 °C | | 0,1 | 0,3 | mA |
| V _{CE0} | | T _j = 25 °C | | 1,4 | 1,6 | V |
| | | T _j = 125 °C | | 1,6 | 1,8 | V |
| r _{CE} | V _{GE} = 15 V | T _j = 25°C | | 11 | 14 | mΩ |
| | | T _j = 125°C | | 15 | 19 | mΩ |
| V _{CE(sat)} | I _{Cnom} = 100 A, V _{GE} = 15 V | T _j = °C _{chiplev.} | | 2,5 | 3 | V |
| C _{ies} | | | | 6,5 | 8,5 | nF |
| C _{oes} | $V_{CE} = 25, V_{GE} = 0 V$ | f = 1 MHz | | 1 | 1,5 | nF |
| C _{res} | | | | 0,5 | 0,6 | nF |
| Q_G | V _{GE} = -8V - +20V | | | 1000 | | nC |
| R _{Gint} | $T_j = ^{\circ}C$ | | | 5 | | Ω |
| t _{d(on)} | | | | 160 | 320 | ns |
| t _r | R_{Gon} = 6,8 Ω | $V_{CC} = 600V$ | | 80 | 160 | ns |
| E _{on} | | I _C = 100A | | 16 | | mJ |
| t _{d(off)} | $R_{Goff} = 6.8 \Omega$ | T _j = 125 °C | | 400 | 520 | ns |
| t _f | | $V_{GE} = -15V$ | | 70 | 100 | ns |
| E _{off} | | | | 12 | | mJ |
| R _{th(j-c)} | per IGBT | | | | 0,15 | K/W |



IGBT Modules

SKM 145GB123D SKM 145GAL123D

Features

- MOS input (voltage controlled)
- N channel, Homogeneous Si
- · Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (10 mm) and creepage distances (20 mm)

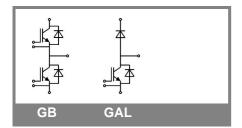
Typical Applications*

- Switching (not for linear use)
- AC inverter drives

| Characteristics | | | | | | |
|-----------------------|--|--|------|------|------|-------|
| Symbol | Conditions | | min. | typ. | max. | Units |
| Inverse D | | | | | | |
| $V_F = V_{EC}$ | $I_{Fnom} = 100 \text{ A}; V_{GE} = 0 \text{ V}$ | | | 2 | 2,5 | V |
| | | $T_j = 125 ^{\circ}C_{\text{chiplev.}}$ | | 1,8 | | V |
| V_{F0} | | T _j = 25 °C | | 1,1 | 1,4 | V |
| | | T _j = 125 °C | | | | V |
| r _F | | T _j = 25 °C | | 9 | 11 | mΩ |
| | | T _j = 125 °C | | | | mΩ |
| I _{RRM} | I _F = 100 A | T _j = 25 °C | | 35 | | A |
| Q _{rr} | di/dt = 1000 A/µs | | | 5 | | μC |
| E _{rr} | V _{GE} = 0 V; V _{CC} = 600 V | | | | | mJ |
| R _{th(j-c)D} | per diode | | | | 0,36 | K/W |
| | eling Diode | | | | | |
| $V_F = V_{EC}$ | $I_{Fnom} = 150 \text{ A}; V_{GE} = 0 \text{ V}$ | | | 2 | 2,5 | V |
| | | $T_j = 125 ^{\circ}C_{\text{chiplev.}}$ | | 1,8 | | V |
| V_{F0} | | T _j = 25 °C | | 1,1 | 1,4 | V |
| | | T _j = 125 °C | | | | V |
| r _F | | T _j = 25 °C | | 9 | 11 | V |
| | | T _j = 125 °C | | | | V |
| I _{RRM} | I _F = 150 A | T _j = 25 °C | | 55 | | A |
| Q _{rr} | .,, | | | 8 | | μC |
| E _{rr} | V _{GE} = 0 V; V _{CC} = 600 V | | | | | mJ |
| $R_{th(j-c)FD}$ | per diode | | | | 0,3 | K/W |
| Module | | | | | | |
| L _{CE} | | | | | 30 | nΗ |
| R _{CC'+EE'} | res., terminal-chip | T _{case} = 25 °C | | 0,75 | | mΩ |
| | | T _{case} = 125 °C | | 1 | | mΩ |
| R _{th(c-s)} | per module | | | | 0,05 | K/W |
| M _s | to heat sink M6 | | 3 | | 5 | Nm |
| M _t | to terminals M5 | | 2,5 | | 5 | Nm |
| w | | | | | 160 | g |

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.





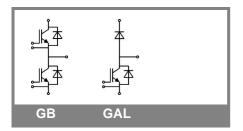
IGBT Modules

SKM 145GB123D SKM 145GAL123D

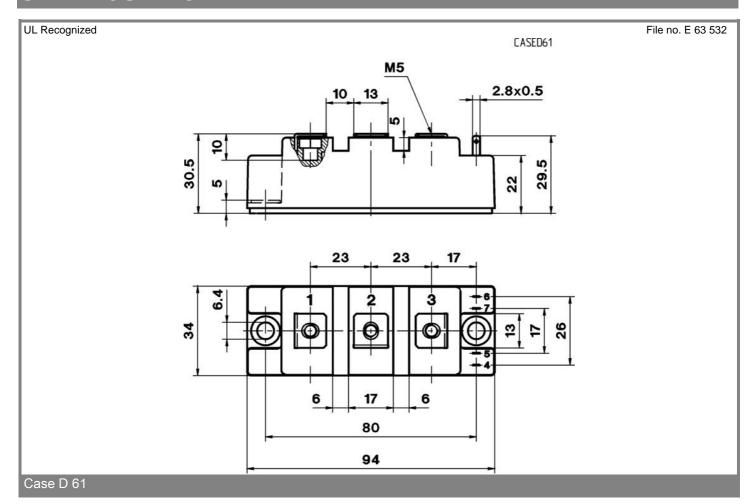
- MOS input (voltage controlled)
- N channel, Homogeneous Si
- · Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (10 mm) and creepage distances (20 mm)

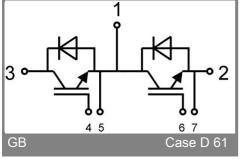
Typical Applications*

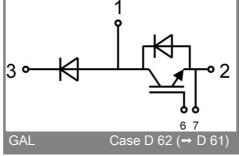
- Switching (not for linear use)
- AC inverter drives



| Z _{th} | lo and the annual | Walter | 111-14- |
|-----------------------|-------------------|--------|---------|
| Symbol | Conditions | Values | Units |
| Z R _i | 1 | | • |
| R _i | i = 1 | 100 | mk/W |
| R_i | i = 2 | 38 | mk/W |
| R_i | i = 3 | 10 | mk/W |
| R_i | i = 4 | 2 | mk/W |
| tau _i | i = 1 | 0,03 | S |
| tau _i | i = 2 | 0,0287 | S |
| tau _i | i = 3 | 0,0012 | s |
| tau _i | i = 4 | 0,0002 | s |
| Z _{th(j-c)D} | | | · |
| R _i | i = 1 | 240 | mk/W |
| R_i | i = 2 | 95 | mk/W |
| R _i | i = 3 | 22 | mk/W |
| R _i | i = 4 | 3 | mk/W |
| tau _i | i = 1 | 0,054 | s |
| tau _i | i = 2 | 0,0113 | s |
| tau _i | i = 3 | 0,0012 | s |
| tau _i | i = 4 | 0,005 | s |







6 25-04-2007 SEI © by SEMIKRON